



Low Distortion, Precision Wide Bandwidth Op Amp

ANALOG DEVICES INC

AD9618

1.1 Scope.

This specification covers the requirements for a low distortion, wide bandwidth operational amplifier. Consult the commercial data sheet for theory and applications information.

1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device	Part Number
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- | | |
|----|-----------------|
| -1 | AD9618S(X)/883B |
| -2 | AD9618T(X)/883B |

1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline:

(X)	Package	Description
Q	Q-8	8-Pin Ceramic DIP
Z	Z-8	8-Pin Ceramic Flatpack (Gull Wing)

1.3 Absolute Maximum Ratings. ($T_A = +25^\circ\text{C}$ unless otherwise noted)

Supply Voltages ($\pm V_S$)	$\pm 7 \text{ V}$
Common-Mode Input Voltage	$\pm V_S$
Differential Input Voltage	3 V
Continuous Output Current*	70 mA
Junction Temperature	+175°C
Operating Temperature Range (Case)	-55°C to +125°C
Storage Temperature Range (Case)	-65°C to +150°C
Lead Temperature (Soldering 10 sec)	+300°C

*Output is short circuit protected to ground, but not to supplies. Continuous short circuit to ground may affect device reliability.

1.5 Thermal Characteristics.

Thermal Resistance $\theta_{JA} = 120^\circ\text{C/W}$ for Flatpack

$\theta_{JC} = 20^\circ\text{C/W}$ for Flatpack

$\theta_{JA} = 110^\circ\text{C/W}$ for Ceramic DIP

$\theta_{JC} = 20^\circ\text{C/W}$ for Ceramic DIP

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Table 1.

Test	Symbol	Device	Design Limit ¹	Sub Group 1	Sub Group 2	Sub Group 3	Sub Group 4, 6	Sub Group 5	Test Condition ²	Units
Input Offset Voltage	V_{OS}	—1		—1.1/+2.2					Measured in Respect to Inverting Input	V/ $^{\circ}$ C min/max
Offset Voltage TC	$V_{OS\ TC}$	All		—4/+25						μ V/ $^{\circ}$ C min/max
Input Bias Current Inverting	I_B	—1		—50/+50						μ A/ $^{\circ}$ C min/max
		—1		—25/+35						
Input Bias Current TC Inverting	$I_B\ TC$	All		—50/+130						nA/ $^{\circ}$ C min/max
Common-Mode Input Range	CMIR	All		± 1.4	± 1.0	± 1.4			$A_V = 1$	V min
Common-Mode Rejection Ratio	CMRR	All					48, 50	44	$V_{IN} = \pm 0.25$ V	dB min
Power Supply Rejection Ratio	PSRR	All					50	50	$\Delta V_S = \pm 5\%$	dB min
Output Current	I_{OUT}	All	60	60	50				50 Ω Load	mA min
Output Voltage Swing	V_{OUT}	All	—3.4	—3.4	—3.4					V max
			+3.4	+3.4	+3.4					V min
Small Signal Bandwidth	SSBW	All					130	130	$V_{OUT} \leq 2$ V p-p	MHz min
Large Signal Bandwidth	LSBW	All	120						$V_{OUT} = 5$ V p-p	MHz min
Output Peaking		All					0.4		<50 MHz; T = T_{MIN} to +25 $^{\circ}$ C	dB max
							0.7		<50 MHz; T = T_{MAX}	
							0.6		>50 MHz; T = T_{MIN} to +25 $^{\circ}$ C	
							1.2		>50 MHz; T = T_{MAX}	
Output Rolloff		All					1.2	1.2	<75 MHz	dB max
Second Harmonic Distortion	HD ₂	All	—75						$V_{OUT} = 2$ V p-p, F = 4.3 MHz	dBc max
			—55						$V_{OUT} = 2$ V p-p, F = 20 MHz	
							—43	—43	$V_{OUT} = 2$ V p-p, F = 60 MHz	
Third Harmonic Distortion	HD ₃	All	—77						$V_{OUT} = 2$ V p-p, F = 4.3 MHz	dBc max
			—62						$V_{OUT} = 2$ V p-p, F = 20 MHz	
							—54	—54	2 V p-p; 60 MHz	
Slew Rate	t_{SR}	All	1400						$V_{OUT} = 4$ V Step	V/ μ s min
Rise/Fall Time	t_{RF}	All	2.6						$V_{OUT} = 2$ V Step	ns max
			2.8						$V_{OUT} = 5$ V Step, +25 $^{\circ}$ C to T_{MAX}	ns max
			3.1						$V_{OUT} = 5$ V Step, T = T_{MIN}	ns max
Overshoot Amplitude		All	10						$V_{OUT} = 2$ V Step	% max

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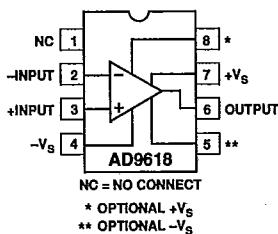
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Test	Symbol	Device	Design Limit ¹	Sub Group 1	Sub Group 2	Sub Group 3	Sub Group 4, 6	Sub Group 5	Test Condition ²	Units
Settling Time	t _{SL}	All	15						2 V Step; to 0.1%	ns max
			23						2 V Step; to 0.02%	nsmax
			16						4 V Step; to 0.1%	ns max
			24						4 V Step; to 0.02%	ns max
V _{CC} Supply Current	+I _S	All		43	43	43			V _{CC} = +5 V	mA max
V _{EE} Supply Current	-I _S	All		43	43	43			V _{EE} = -5 V	mA max

NOTES

¹Indicates specification which is guaranteed but not tested. Value shown is over full temperature range.²Unless otherwise noted, A_v = +10; ±V_S = ±5 V; R_f = 1,000 Ω; R_{LOAD} = 100 Ω.

3.2.1 Functional Block Diagram and Terminal Assignments.



3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (D-49).

4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).

